June 1999



FDG6324L **Integrated Load Switch**

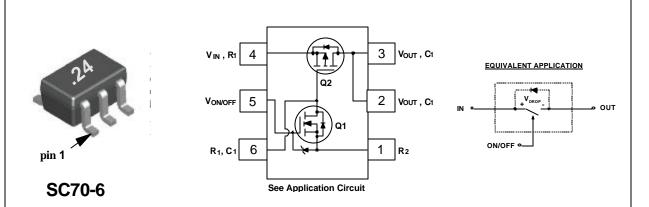
General Description

This device is intended to be configured as a load switch and is particularly suited for compact computer peripheral switching applications where 3V to 20V input and 0.6A output current capability are needed. This device features a small N-Channel MOSFET (Q1) together with a large P-Channel Power MOSFET (Q2) in a single SC70-6 package.

Features

- V_{DROP} =0.2V @ V_{IN} =12V, I_{L} =0.36A. $R_{(ON)}$ =0.55 Ω . V_{DROP} =0.2V @ $V_{IN}=5V$, $I_{L}=0.27A$. $R_{(ON)}=0.75\Omega$.
- Very small package outline (SC70-6).
- Control MOSFET (Q1) includes Zener protection for ESD ruggedness (> 6KV Human Body Model).
- High density cell design for extremely low on-resistance.





Symbol	Parameter	FDG6324L	Units
V _{IN}	Input Voltage Range	3 - 20	V
V _{ON/OFF}	On/Off Voltage Range	2.5 - 8	V
L	Load Current - Continuous (Note 1)	0.6	A
	- Pulsed (No	ote 1 & 3) 1.8	
P _D	Maximum Power Dissipation (Note 2)	0.3	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	°C
ESD	Electrostatic Discharge Rating Human Body Model (100pf/1500Ohm)	6	kV
THERMA	L CHARACTERISTICS	<u> </u>	•
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 2)	415	°C/W

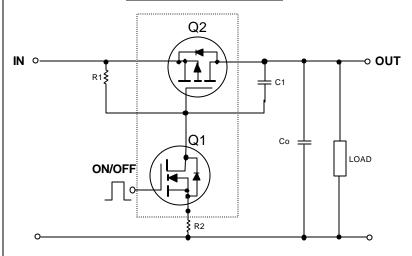
Symbol	Parameter	Conditions	Min	Тур	Max	Units
OFF CHAI	RACTERISTICS					
I _{FL}	Forward Leakage Current	V _{IN} = 20 V, V _{ON/OFF} = 0 V			1	μΑ
ON CHAR	ACTERISTICS (Note 3)		*	•	•	
V _{DROP}	Conduction Voltage Drop	V_{IN} = 12 V, $V_{ON/OFF}$ = 3.3 V, I_L = 0.36 A		0.14	0.2	V
		V _{IN} = 5 V, V _{ON/OFF} = 3.3 V, I _L = 0.27 A		0.16	0.2	
R _(ON)	Q ₂ - Static On-Resistance	V _{GS} = -12 V, I _D = -0.6 A		0.37	0.55	Ω
		V _{GS} = -5 V, I _D = -0.5 A		0.58	0.75	
IL	Load Current	$V_{DROP} = 0.2 \text{ V}, V_{IN} = 12 \text{ V}, V_{ON/OFF} = 3.3 \text{ V}$	0.36			Α
		$V_{DROP} = 0.2 \text{ V}, V_{IN} = 5 \text{ V}, V_{ON/OFF} = 3.3 \text{ V}$	0.27			1

Notes:

- 1. Range of $V_{\rm in}$ can be up to 25V, but $R_{\rm 1}$ and $R_{\rm 2}$ must be scaled such that $V_{\rm GS}$ of Q2 does not exceed -20V.
- 2. $R_{\theta,A}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta,c}$ is guaranteed by design while $R_{\theta,c,A}$ is determined by the user's board design. Thermal ratings based on minimum mounting pad.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%

FDG6324L Load Switch Application

APPLICATION CIRCUIT



External Component Recommendation

For $Co \le 1uF$ applications:

R1 is required to turn Q2 off.

R2 and C1 are optional for slew rate control.

First select R2, 100 -1K Ω , for slew rate control.

Then select R1 such that the ratio R1/R2 is maintained between 10-100.

SPICE model (FDG6324L.MOD) available at www.fairchildsemi.com.

Typical Electrical Characteristics ($T_A = 25~^{\circ}\text{C}$ unless otherwise noted)

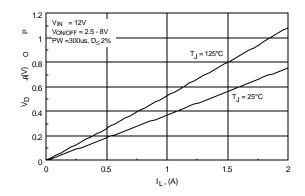


Figure 1. Conduction Voltage Drop Variation with Load Current.

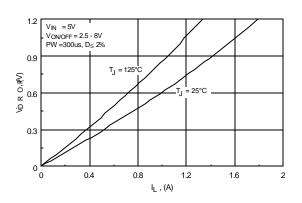


Figure 2. Conduction Voltage Drop Variation with Load Current.

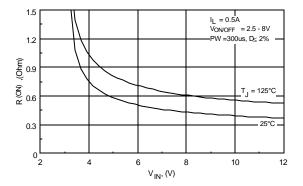


Figure 3. On-Resistance Variation with Input Voltage.

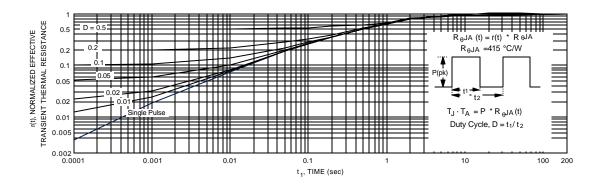


Figure 4. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 2. Transient thermal response will change depending on the circuit board

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